

date 03/30/2017

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MODEL: HSS-B20-085H | DESCRIPTION: HEAT SINK

FEATURES

- TO-220 package
- round hole for component attachment
- solder pin for secure PCB mounting
- black anodized finish





thermal resistance¹ power dissipation¹ @ 1 W, 400 LFM @ 75°C ∆T, @ 75°C ∆T, @ 1 W, @ 1 W, 200 LFM nat conv nat conv nat conv (°C/W) (°C/W) (°C/W) (°C/W) (W) HSS-B20-085H 22.06 26.05 7.46 5.20 3.40

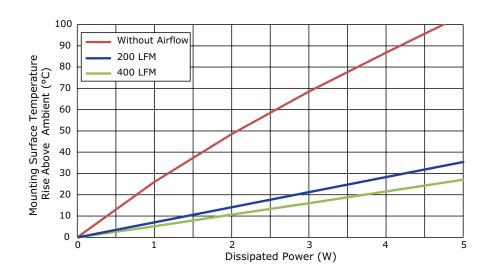
Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	26.05	7.46	5.20
2	48.51	14.24	10.69
3	68.48	21.48	16.04
4	86.75	28.25	21.52
5	104.54	35.39	27.11

Ths: "hot spot" temperature measured on the heatsink

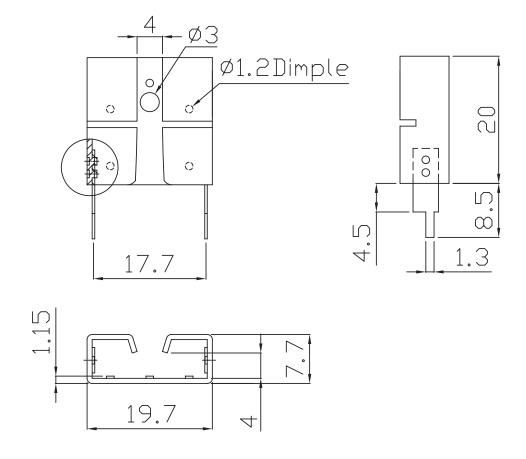
Ta: ambient temperature



MECHANICAL DRAWING

units: mm tolerance: ±0.5 mm

MATERIAL	AL5052
FINISH	black anodized
THICKNESS	0.8 mm
PIN MATERIAL	brass
PIN PLATING	tin
WEIGHT	2.0 g



REVISION HISTORY

rev.	description	date
1.0	initial release	03/30/2017

The revision history provided is for informational purposes only and is believed to be accurate.



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CUI offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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